MMBFJ175LT1

Preferred Device

JFET Chopper

P-Channel - Depletion

Features

• Pb-Free Package is Available

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain-Gate Voltage	V_{DG}	25	V
Reverse Gate-Source Voltage	V _{GS(r)}	-25	V

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board, (Note 1) T _A = 25°C Derate above 25°C	P _D	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. $FR-5 = 1.0 \times 0.75 \times 0.062$ in.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit		
OFF CHARACTERISTICS						
Gate – Source Breakdown Voltage (V _{DS} = 0, I _D = 1.0 μA)	V _{(BR)GSS}	30	-	V		
Gate Reverse Current (V _{DS} = 0 V, V _{GS} = 20 V)	I _{GSS}	-	1.0	nA		
Gate – Source Cutoff Voltage (V _{DS} = 15, I _D = 10 nA)	V _{GS(OFF)}	3.0	6.0	V		

ON CHARACTERISTICS

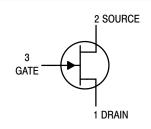
Zero Gate-Voltage I (V _{GS} = 0, V _{DS} =	I _{DSS}	7.0	60	mA	
Drain Cutoff Current (V _{DS} = 15 V, V _G	I _{D(off)}	-	1.0	nA	
Drain Source On Resistance (I _D = 500 μA)		r _{DS(on)}	-	125	Ω
Input Capacitance	V -0 V -10V	C _{iss}	-	11	
Reverse Transfer Capacitance	$V_{DS} = 0, V_{GS} = 10V$ f = 1.0 MHz	C _{rss}	_	5.5	pF

2. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.



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SOT-23 (TO-236) CASE 318 STYLE 10

MARKING DIAGRAM



6W = Device Code M = Date Code* ■ = Pb-Free Package

(Note: Microdot may be in either location)
*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
MMBFJ175LT1	SOT-23	3,000 / Tape & Reel
MMBFJ175LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel

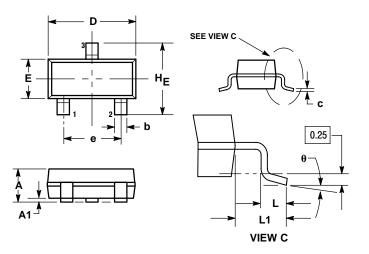
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

MMBFJ175LT1

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 ISSUE AN



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
 V14 FM 1082
- Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- 4. 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08.

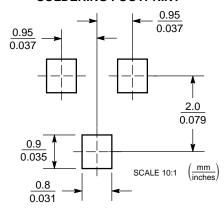
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 10:

PIN 1. DRAIN

- 2. SOURCE
- 3. GATE

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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